2:1 MIPI D-PHY (1.5 Gbps) 4-Data Lane Switch

The NL3HS644 is a 4-data lane MIPI, D-PHY switch. This single-pole double-throw (SPDT) switch is optimized for switching between 2 high-speed or low-power MIPI sources. The NL3HS644 is designed for MIPI specifications and allows connection to a CSI or DSI module.

Features

• Operating Supply: $V_{CC} = 1.65 \text{ V}$ to 4.5 V

Switch Signal Range: 0 to V_{CC}
Signal Types: MIPI, D–PHY

• ON-Resistance:

 $R_{ON} = 8 \Omega$ (Typ) HS MIPI $R_{ON} = 7.9 \Omega$ (Typ) LP MIPI

• ON–Resistance Mismatch:

 $\Delta R_{ON} = 0.09 \ \Omega \ (Typ) \ HS \ MIPI$ $\Delta R_{ON} = 0.17 \ \Omega \ (Typ) \ LP \ MIPI$

• ON Resistance Flatness:

 $R_{ON_FLAT} = 0.03 \ \Omega \ (Typ) \ HS \ MIPI$ $R_{ON \ FLAT} = 0.46 \ \Omega \ (Typ) \ LP \ MIPI$

• Supply Current: $I_{CC} = 55 \mu A \text{ (Max)}$

• Hi–Z Supply Current: $I_{CCZ} = 5 \mu A (Max)$

• Off–Isolation: $O_{IRR} = -27 \text{ dB (Typ)}$

• Crosstalk: $X_{TALK} = -28 \text{ dB (Typ)}$

• Bandwidth: BW = 1,050 MHz (Typ)

• Channel to Channel Skew: $t_{SK} = 63 \text{ ps (Typ)}$

• ON Capacitance: C_{ON} = 12.6 pF

• 36-Ball WLCSP Package, 2.36 mm x 2.36 mm

• This device is Pb–Free, Halogen–Free/BFR–Free and are RoHS–Compliant



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WLCSP36 FC SUFFIX CASE 567LR

MARKING DIAGRAM



XXXXXX = Device Code

A = Assembly Location

WL = Wafer Lot Y = Year

WW = Work Week

= Pb–Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 8 of this data sheet.

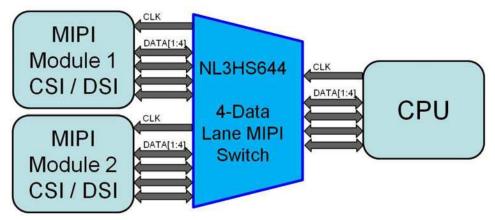
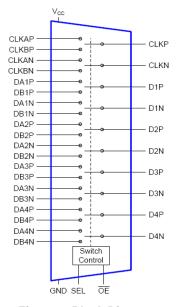


Figure 1. Typical Application - Mobile Phone

FUNCTION TABLE

ŌĒ	SEL	FUNCTION
L	L	CLKP = CLKAP, CLKN = CLKAN, DnP = DAnP, DnN = DAnN
L	Н	CLKP = CLKBP, CLKN = CLKBN, DnP = DBnP, DnN = DBnN
Н	Х	CLKAP/CLKAN, CLKBP/CLKBN, DAnP/DAnN, DBnP/DBnN Ports at High Impedance



A (CLKN) (CLKP) (CLKAP) (DA1P) (DA2P) (DA2N)

B (D1N) (D1P) (CLKAN) (DA1N) (DA3P) (DA3N)

C (D2N) (D2P) (NC) (VCC) (DA4P) (DA4N)

D (D3N) (D3P) (GND) (NC) (CLKBN) (CLKBP)

E (D4N) (D4P) (DB4P) (DB3P) (DB1N) (DB1P)

F (OE) (SEL) (DB4N) (DB3N) (DB2N) (DB2P)

1 2 3 4 5 6

Figure 2. Block Diagram

Figure 3. Pinout (Top Through View)

PIN ASSIGNMENT

Pin Name	Ball			Description
CLKP / CLKN	A2 / A1	Common Clock	k Path	
D1P / D1N	B2 / B1	Common Data	Path 1	
D2P / D2N	C2 / C1	Common Data	Path 2	
D3P / D3N	D2 / D1	Common Data	Path 3	
D4P / D4N	E2 / E1	Common Data	Path 4	
CLKAP / CLKAN	A3 / B3	A-Side Clock F	Path	
DA1P / DA1N	A4 / B4	A-Side Data Pa	ath 1	
DA2P / DA2N	A5 / A6	A-Side Data Pa	ath 2	
DA3P / DA3N	B5 / B6	A-Side Data Pa	ath 3	
DA4P / DA4N	C5 / C6	A-Side Data Pa	ath 4	
CLKBP / CLKBN	D6 / D5	B-Side Clock F	Path	
DB1P / DB1N	E6 / E5	B-Side Data Pa	ath 1	
DB2P / DB2N	F6 / F5	B-Side Data Pa	ath 2	
DB3P / DB3N	E4 / F4	B-Side Data Pa	ath 3	
DB4P / DB4N	E3 / F3	B-Side Data Pa	ath 4	
SEL	F2	Control Pin	SEL = L:	CLKP = CLKAP, CLKN = CLKAN, DnP = DAnP, DnN = DAnN
			SEL = H:	CLKP = CLKBP, CLKN = CLKBN, DnP = DBnP, DnN = DBnN
ŌĒ	F1	Output Enable		
VCC	C4	Power		
GND	D3	Ground		
NC	C3 / D4	No Connect		

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CC}	Positive DC Supply Voltage	−0.5 to +5.5	V
V _{IS}	Analog Input Voltage	–0.5 to V _{CC} + 0.5	V
V _{IN}	Digital Control Input Voltage (SEL or OE)	−0.5 to +5.5	V
los	Switch Output Current	50	mA
I _{IOK}	Switch Input/Output Diode Current	- 50	mA
I _{IK}	Control Input Diode Current	±50	mA
Ts	Storage Temperature	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	4.5	V
V _{IS}	Switch Input / Output Voltage			V
	HS Mode	0.1	0.3	
	LP Mode	0	1.2	
V _{IN}	Digital Control Input Voltage (SEL or OE) (Note 1)	GND	V _{CC}	V

^{1.} Control input must be held High or Low. It must not float.

DC ELECTRICAL CHARACTERISTICS

Voltages referenced to GND. All typical values are at $T_A = 25$ °C unless otherwise specified.

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
DIGITAL CO	NTROL SECTION (SEL or $\overline{\text{OE}}$)						
V _{IK}	Clamp Diode Voltage	I _{IN} = -18 mA	2.8			-1.2	V
V _{IH}	Input Voltage High		1.65 – 4.5	1.0			V
V _{IL}	Input Voltage Low		1.65 – 4.5			0.4	V
I _{IN}	Input Leakage Current	$V_{IN} = 0 \text{ V to } V_{CC}$	1.65 – 4.5			±100	nA
SWITCHES							
R _{ON_MIPI_}	Switch ON Resistance	$I_{ON} = -10 \text{ mA}, \overline{OE} =$	1.8		9	12	Ω
HS	for HS MIPI Applications	0 V, SEL = V_{CC} or 0 V,	2.5		8	9	
	(Note 2)	CLKA, CLKB, DBn or	3.6		8	9	
		DAn = 0.1, 0.2, 0.3 V	4.5		8	9	
R _{ON_MIPI_LP}	Switch ON Resistance	$I_{ON} = -10 \text{ mA}, \overline{OE} =$	1.8		9.5	12	Ω
	for LP MIPI Applications	0 V, SEL = V_{CC} or 0 V,	2.5		8.5	10	
	(Note 2)	CLKA, CLKB, DBn or	3.6		7.9	9	
		DAn = 0, 0.6, 1.2 V	4.5		7.6	9	
$\Delta R_{ON_{-}}$	ON Resistance Matching	$I_{ON} = -10 \text{ mA}, \overline{OE} =$	1.8		0.02		Ω
MIPI_HS	Between HS MIPI	0 V, SEL = V_{CC} or 0 V,	2.5		0.09		1
	Channels (Note 3)	CLKA, CLKB, DBn or	3.6		0.09		1
		DAn = 0.1, 0.2, 0.3 V	4.5		0.08		1

^{2.} Measured by the voltage drop between A and B pins at the indicated current through the switch. ON resistance is determined by the lower of the voltage on the two (A or B ports).

^{3.} Guaranteed by characterization.

DC ELECTRICAL CHARACTERISTICS

Voltages referenced to GND. All typical values are at $T_A = 25$ °C unless otherwise specified.

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
SWITCHES			•	•			
$\Delta R_{ON_{-}}$	ON Resistance Matching	$I_{ON} = -10 \text{ mA}, \overline{OE} =$	1.8		0.17		Ω
MIPI_LP	Between LP MIPI	0 V, SEL = V_{CC} or 0 V,	2.5		0.12		
	Channels (Note 3)	CLKA, CLKB, DBn or	3.6		0.17		1
		DAn = 0, 0.6, 1.2 V	4.5		0.09		1
R _{ON_FLAT_} MIPI_HS	ON Resistance Flatness	$I_{ON} = -10 \text{ mA}, \overline{OE} =$	1.8		0.23		Ω
	for HS MIPI Channels	0 V, SEL = V_{CC} or 0 V,	2.5		0.11		1
	(Note 3)	CLKA, CLKB, DBn or	3.6		0.03		
		DAn = 0.1, 0.2, 0.3 V	4.5		0.02		1
R _{ON_FLAT_}	ON Resistance Flatness	$I_{ON} = -10 \text{ mA}, \overline{OE} =$	1.8		2.09		Ω
MIPI_LP	for LP MIPI Channels	0 V, SEL = V_{CC} or 0 V,	2.5		1.19		1
	(Note 3)	CLKA, CLKB, DBn or	3.6		0.46		1
		DAn = 0, 0.6, 1.2 V	4.5		0.08		1
I _{NO(OFF)} , I _{NC(OFF)}	OFF Leakage Current (CLKAn, DAn, CLKBn, DBn)	CLKn, Dn = 0.3 V, V_{CC} – 0.3 V, CLKAn, DAn, or CLKBn; DBn = V_{CC} – 0.3 V, 0.3 V or Floating; \overline{OE} = 0 V	1.65 – 4.5			±100	nA
I _{A(ON)}	ON Leakage Current of Common Ports (CLKn, Dn)	CLKn, Dn = 0.3 V, V_{CC} – 0.3 V, CLKAn, DAn, or CLKBn; DBn = V_{CC} – 0.3 V, 0.3 V or Floating; \overline{OE} = 0 V	1.65 – 4.5			±100	nA
V _{IK}	Clamp Diode Voltage	I _{IN} = -18 mA	2.8			-1.2	V
l _{OZ}	Off–State Leakage Current	$0 \le CLKn$, Dn, CLKAn, CLKBn, DAn, DBn ≤ 3.6 V; $\overline{OE} = High$	4.5			±100	nA
SUPPLY CU	RRENTS						
I _{CCZ}	Quiescent Hi–Z Supply Current	$V_{IN} = 0$ or V_{CC} , $I_{OUT} = 0$	4.5			0.5	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = 0$ or V_{CC} , $I_{OUT} = 0$	2.5 to 4.5			55	μΑ
			1.8			30	1
I _{CCT}	Increase in I _{CC} Current per	V_{SEL} , $V(\overline{OE}) = 1.65 V$	4.5			4.0	μΑ
	Control Voltage and V _{CC}		2.5	0.1		1.0	1

Measured by the voltage drop between A and B pins at the indicated current through the switch. ON resistance is determined by the lower of the voltage on the two (A or B ports).
 Guaranteed by characterization.

$\textbf{AC ELECTRICAL CHARACTERISTICS} \text{ All typical values are for } V_{CC} = 3.3 \text{ V at } T_{A} = 25^{\circ}C \text{ unless otherwise specified.}$

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
t _{INIT}	Initialization Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{IS} = 1.2 V$	2.5 to 4.5	100			μs
	V _{CC} to Output (Notes 4, 5)	Figure 4	1.8	150			
t _{EN}	Enable Turn-On Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{IS} = 1.2 V$	2.5 to 4.5		120	200	μs
	OE to Output	Figure 5	1.8		250	500	
t _{DIS}	Disable Turn-Off Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{IS} = 1.2 V$	2.5 to 4.5		25	50	ns
	OE to Output	Figure 5	1.8		50	90	
t _{ON}	Turn-On Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{IS} = 1.2 V$	2.5 to 4.5		50	100	ns
	SEL to Output	Figure 5	1.8		75	125	
t _{OFF}	Turn-Off Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{IS} = 1.2 V$	2.5 to 4.5		50	200	ns
	SEL to Output	Figure 5	1.8		200	325	
t _{BBM}	Break-Before-Make Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{IS} = 1.2 V$ Figure 6		10	50		ns
O _{IRR}	Off–Isolation for MIPI (Note 4)	$R_L = 50 \Omega$, $f = 750 MHz$, $\overline{OE} = V_{CC}$, $V_{IS} = -1 dBm (200 mV_{PP})$	1.65 to 4.5		-27		dB
X _{TALK}	Crosstalk for MIPI (Note 4)	$R_L = 50 \Omega$, $f = 750 MHz$, $V_{IS} = -1 dBm (200 mV_{PP})$	1.65 to 4.5		-28		dB
BW	-3 dB Bandwidth (Note 4)	$R_L = 50 \Omega, C_L = 0 pF$	3.0	900	1050		MHz
S _{DD21}	Differential Data Rate	Inter-Operability Data Rate	3.0		1.5		Gbps

HIGH SPEED-RELATED AC ELECTRICAL CHARACTERISTICS

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
t _{SK(O)}	Channel-to-Channel Single-Ended Skew (Note 6)	TDR-Based Method $(V_{IS} = 0.2 V_{PP}, C_L = C_{ON})$ Figure 7	3.3		63	67	ps
t _{SK(P)}	Skew of Opposite Transitions of the Same Output (Note 6)	TDR-Based Method (V _{IS} = 0.2 V _{PP} , C _L = C _{ON}) Figure 8	3.3		17	31	ps

^{6.} Guaranteed by characterization.

CAPACITANCE

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 0 V, f = 1 MHz	3.3		14.9		pF
C _{ON}	Out ON Capacitance	$V_{CC} = 3.3 \text{ V}, \overline{OE} = 0 \text{ V}, f = 1 \text{ MHz}$	3.3		12.6		pF
C _{OFF}	Out OFF Capacitance	$V_{CC} = 3.3 \text{ V}, \overline{OE} = 3.3 \text{ V}, f = 1 \text{ MHz}$	3.3		7.4		pF

^{4.} Guaranteed by characterization.
5. Wait time required after V_{CC} power–up to operating level before data access is valid.

Timing Diagrams

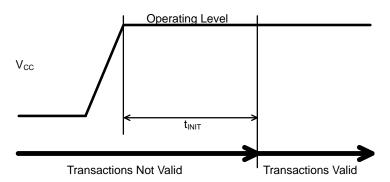


Figure 4. t_{INIT} , Initialization Time

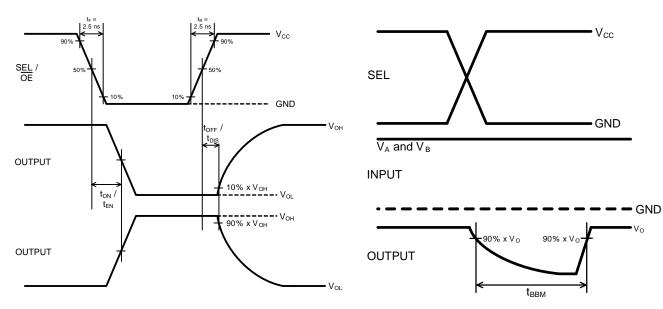


Figure 5. t_{EN}, t_{DIS}, t_{ON}, t_{OFF} Times

Figure 6. t_{BBM}, Break-Before-Make Time

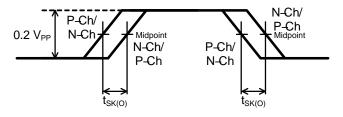


Figure 7. t_{SK(O)}, Channel-to-Channel Single-Ended

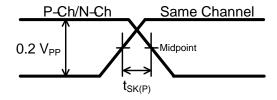


Figure 8. $t_{SK(P)}$, Same Channel Opposite Transitions

Eye Diagrams

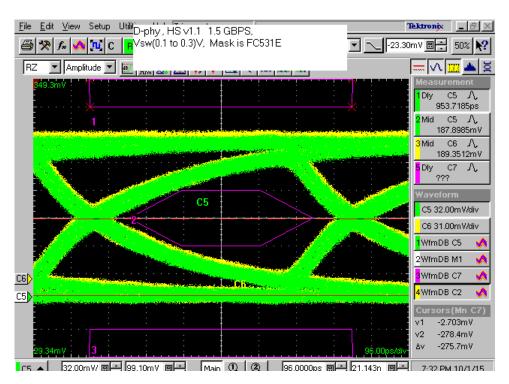


Figure 9. D-PHY HS 1.5 Gbps with Eye Mask

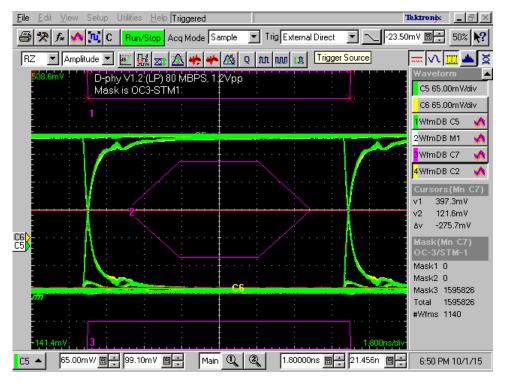


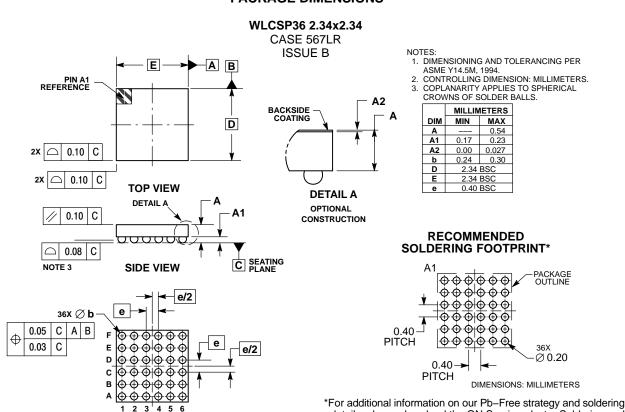
Figure 10. D-PHY LP 80 Mbps with Eye Mask

DEVICE ORDERING INFORMATION

Device Order Number	Device Code	Package Type	Tape & Reel Size [†]
NL3HS644FCTAG	3HS644	36-ball WLCSP (Pb-Free)	3000 / Tape & Reel
NL3HS644BFCTAG (Backside Coated)	HS644B	36-ball WLCSP (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



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